

C1812C823GATACTU

Aliases (C1812C823GATAC7800)

Specifications

Insulation Resistance

SMD Comm X8G HT150C, Ceramic, 0.082 uF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	2mm +/-0.20mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

0.082 uF
1 kHz 1.0Vrms
2%
250 VDC
625 VDC
-55/+150°C
X8G
30 ppm/C, 1kHz 1.0Vrms
0.1% 1 kHz 1.0Vrms
0% Loss/Decade Hour: Referee Time is 1000 Hours

12.1951 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

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